



STP120NF10 - STB120NF10 STW120NF10

N-channel 100V - 0.009Ω - 120A - TO-247 - TO-220 - D²PAK
STripFET™ II Power MOSFET

General features

Type	V _{DSS}	R _{DS(on)}	I _D
STW120NF10	100V	<0.0105Ω	120A
STP120NF10	100V	<0.0105Ω	120A
STB120NF10	100V	<0.0105Ω	120A

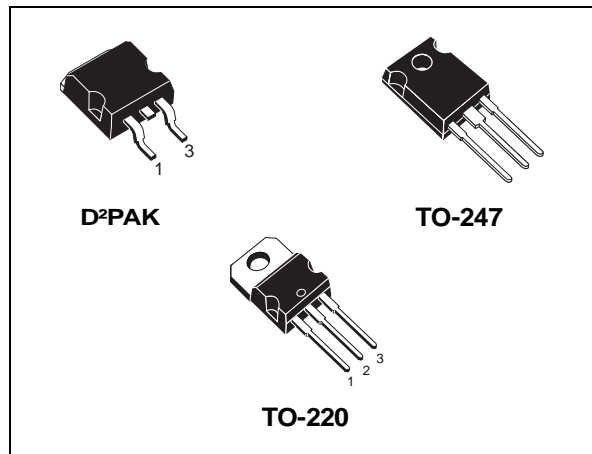
- Exceptional dv/dt capability
- 100% avalanche tested
- Application oriented characterization

Description

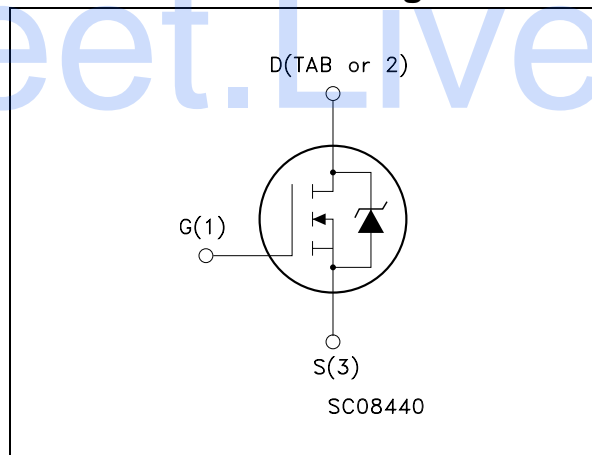
This Power MOSFET series realized with STMicroelectronics unique STripFET™ process has specifically been designed to minimize the on-resistance. It is therefore suitable as primary switch in advanced high-efficiency, high-frequency isolated DC-DC converters for Telecom and Computer application. It is also intended for any applications with low gate drive requirements.

Applications

- Switching application



Internal schematic diagram



Order codes

Sales Type	Marking	Package	Packaging
STW120NF10	W120NF10	TO-247	Tube
STP120NF10	P120NF10	TO-220	Tube
STB120NF10	B120NF10	D ² PAK	Tape & reel

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1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage ($V_{GS} = 0$)	100	V
V_{DGR}	Drai-gate Voltage ($R_{GS}=20k\Omega$)	100	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current (continuous) at $T_C = 25^\circ\text{C}$	120	A
I_D	Drain Current (continuous) at $T_C=100^\circ\text{C}$	85	A
$I_{DM}^{(1)}$	Drain Current (pulsed)	480	A
P_{TOT}	Total Dissipation at $T_C = 25^\circ\text{C}$	312	W
	Derating Factor	2.08	W/°C
$dv/dt^{(2)}$	Peak Diode Recovery voltage slope	10	V/ns
$E_{AS}^{(3)}$	Single Pulse Avalanche Energy	550	mJ
T_J	Operating Junction Temperature	-55 to 175	°C
T_{stg}	Storage Temperature		
T_L	Maximum Lead Temperature for Soldering Purpose	300	°C

1. Pulse width limited by safe operating area.
2. $I_{SD} \leq 120\text{A}$, $di/dt \leq 300\text{A}/\mu\text{s}$, $V_{DD}=80\%V_{(BR)DSS}$
3. Starting $T_J = 25^\circ\text{C}$, $I_D=60\text{A}$, $V_{DD}=50\text{V}$

Table 2. Thermal resistance

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case Max	0.48	°C/W
$R_{thj-amb}$	Thermal resistance junction-ambient Max	62.5	°C/W

2 Electrical characteristics

($T_{CASE}=25^{\circ}C$ unless otherwise specified)

Table 3. On/off states

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu A, V_{GS} = 0$	100			V
I_{DSS}	Zero Gate Voltage Drain Current ($V_{GS} = 0$)	$V_{DS} = \text{Max Rating},$ $V_{DS} = \text{MaxRating} @ 125^{\circ}C$			1 10	μA μA
I_{GSS}	Gate Body Leakage Current ($V_{DS} = 0$)	$V_{GS} = \pm 20V$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2		4	V
$R_{DS(on)}$	Static Drain-Source On Resistance	$V_{GS} = 10V, I_D = 60A$		0.009	0.0105	Ω

Table 4. Dynamic

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$g_{fs}^{(1)}$	Forward Transconductance	$V_{DS} = 25V, I_D = 60A$		90		S
C_{iss}	Input Capacitance	$V_{DS} = 25V, f = 1 \text{ MHz}, V_{GS} = 0$		5200		pF
C_{oss}	Output Capacitance			785		pF
C_{rss}	Reverse Transfer Capacitance			325		pF
Q_g	Total Gate Charge	$V_{DD} = 80V, I_D = 120A$		172	233	nC
Q_{gs}	Gate-Source Charge	$V_{GS} = 10V$		32		nC
Q_{gd}	Gate-Drain Charge	(see Figure 7)		64		nC

1. Pulsed: pulse duration=300 μs , duty cycle 1.5%

Table 5. Switching times

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=50V, I_D=60A,$ $R_G=4.7\Omega, V_{GS}=10V$ (see Figure 12)		25		ns
t_r	Rise Time			90		ns
$t_{d(off)}$	Turn-off Delay Time			132		ns
t_f	Fall Time			68		ns

Table 6. Source drain diode

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
I_{SD}	Source-drain Current				120	A
$I_{SDM}^{(1)}$	Source-drain Current (pulsed)				480	A
$V_{SD}^{(2)}$	Forward on Voltage	$I_{SD}=120A, V_{GS}=0$			1.3	V
t_{rr}	Reverse Recovery Time	$I_{SD}=120A,$ $di/dt = 100A/\mu s,$ $V_{DD}=40V, T_j=150^\circ C$ (see Figure 14)		152		ns
Q_{rr}	Reverse Recovery Charge			760		nC
I_{RRM}	Reverse Recovery Current			10		A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration=300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

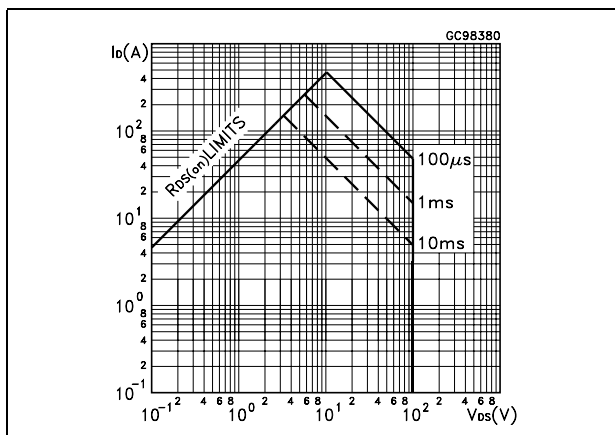


Figure 2. Thermal impedance

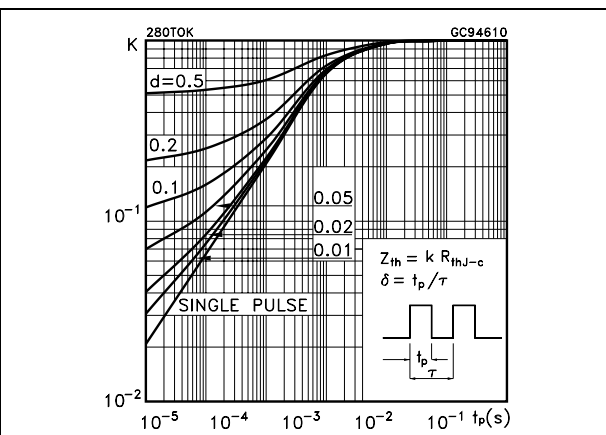


Figure 3. Output characteristics

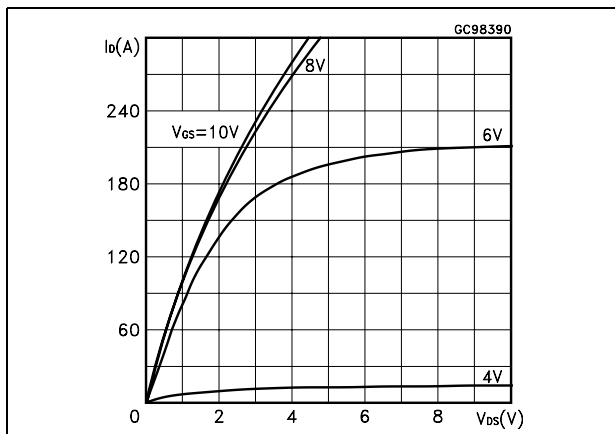


Figure 4. Transfer characteristics

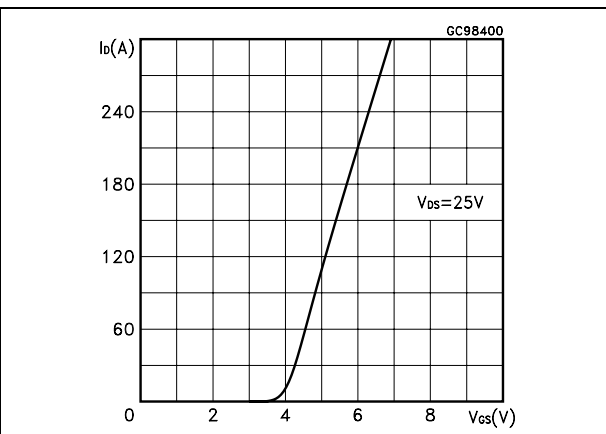


Figure 5. Normalized $B_{V_{DS}}$ vs temperature

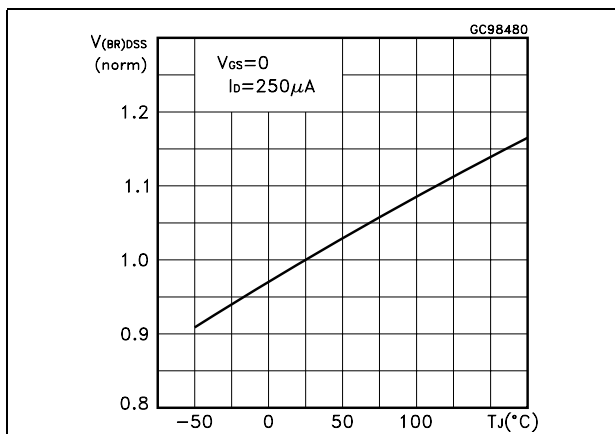


Figure 6. Static drain-source on resistance

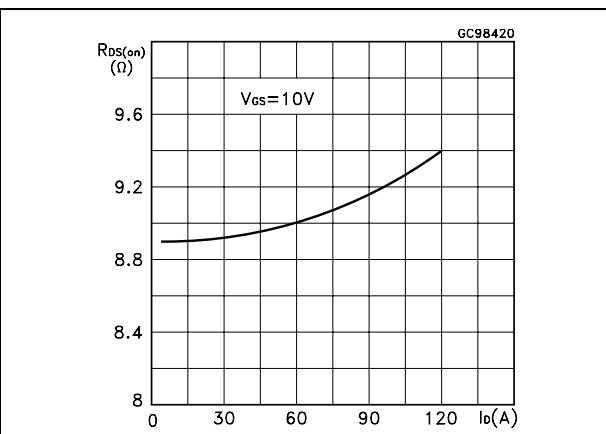


Figure 7. Gate charge vs gate-source voltage Figure 8. Capacitance variations

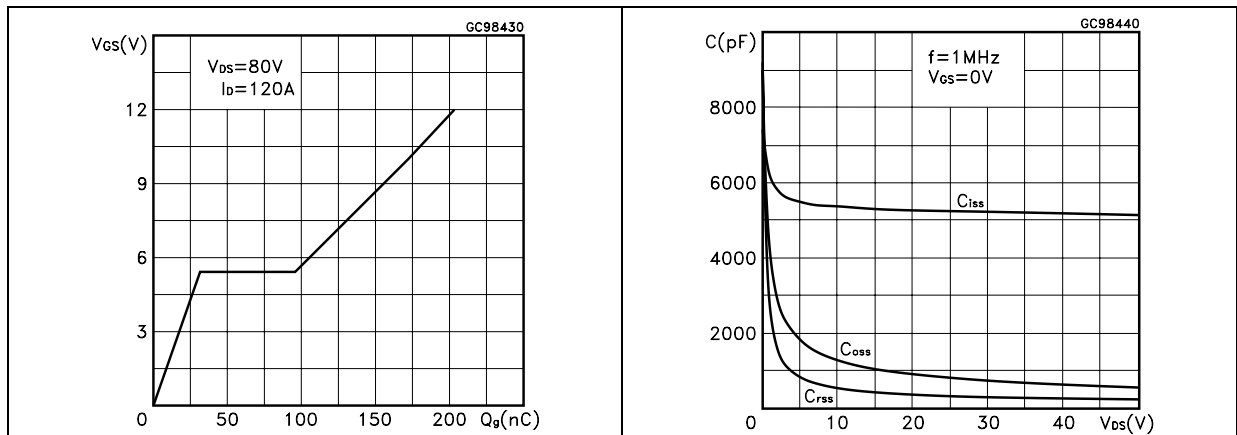


Figure 9. Normalized gate threshold voltage vs temperature Figure 10. Normalized on resistance vs temperature

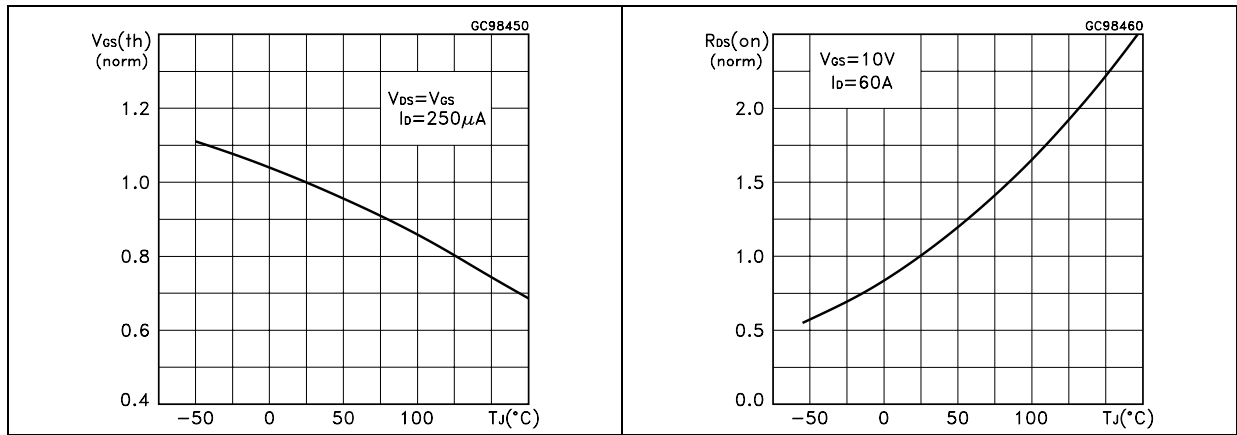
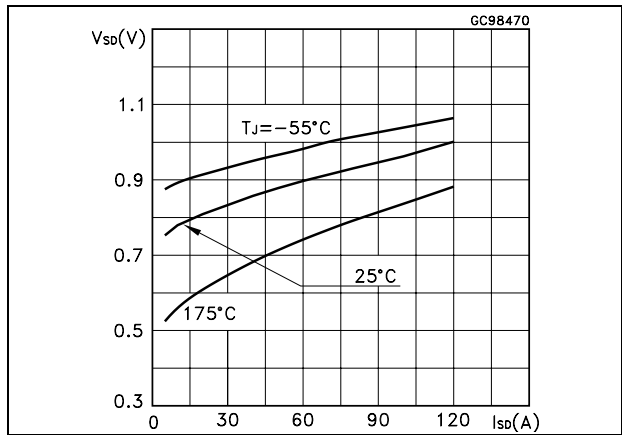


Figure 11. Source-drain diode forward characteristics



3 Test circuit

Figure 12. Switching times test circuit for resistive load

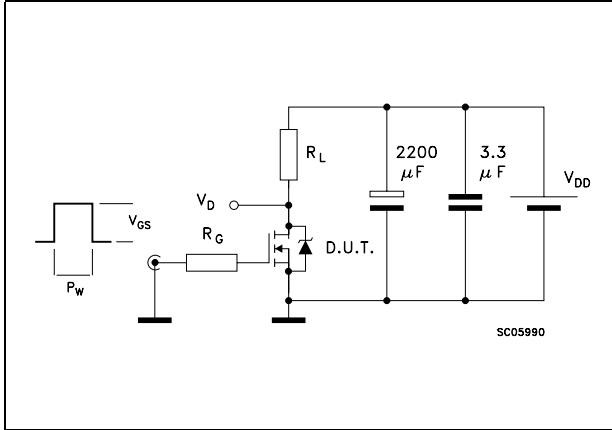


Figure 13. Gate charge test circuit

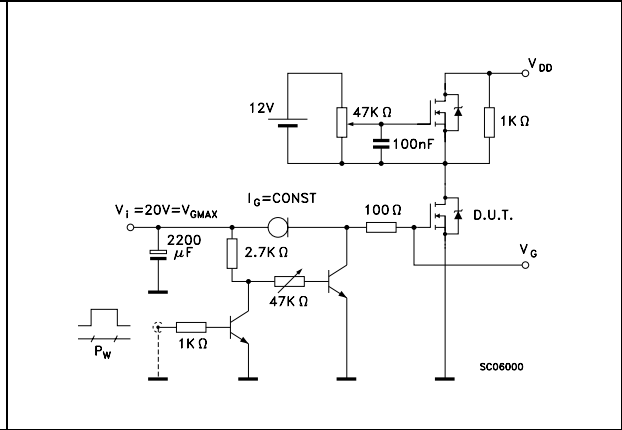


Figure 14. Test circuit for inductive load switching and diode recovery times

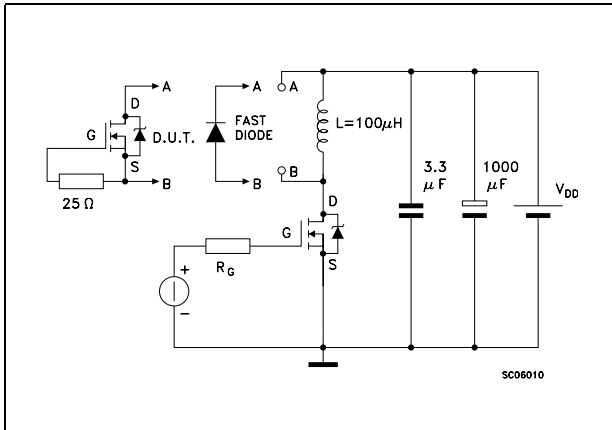


Figure 15. Unclamped inductive load test circuit

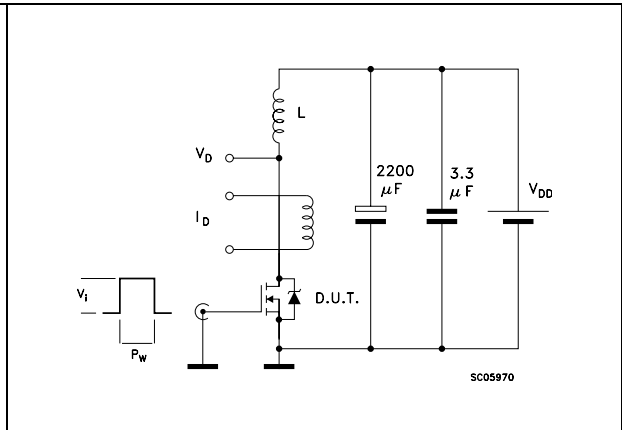


Figure 16. Unclamped inductive waveform

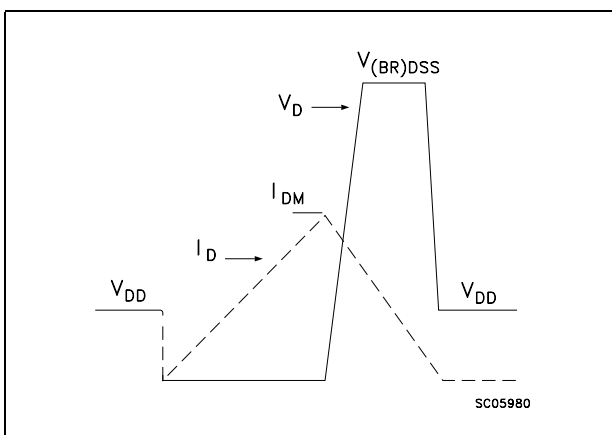
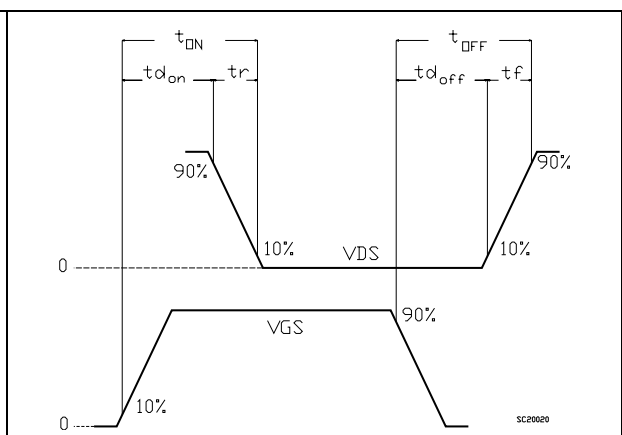


Figure 17. Switching time waveform

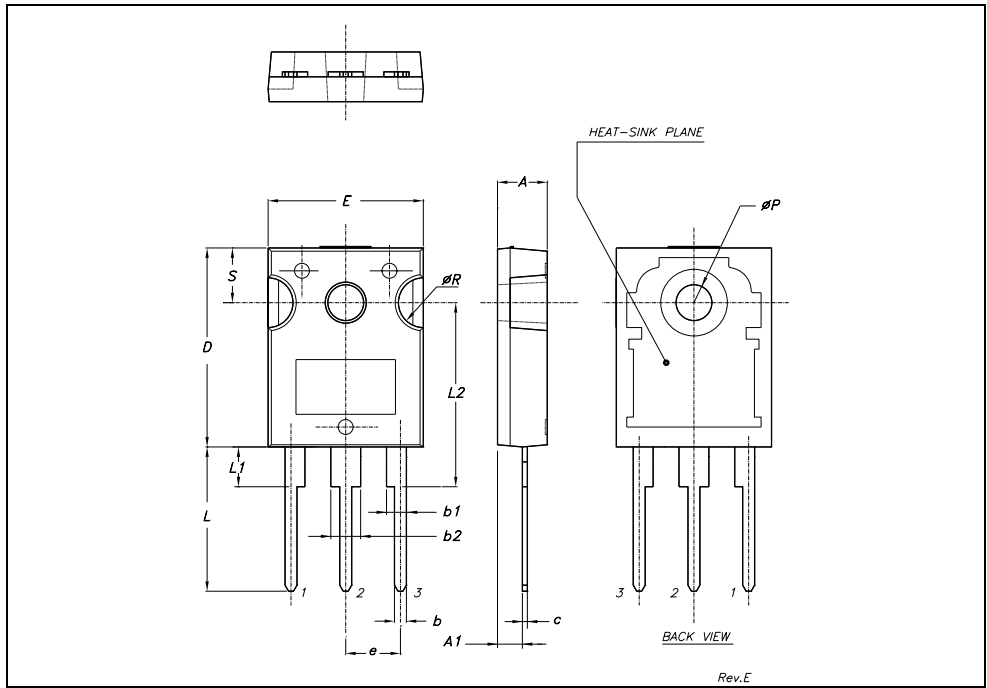


4 Package mechanical data

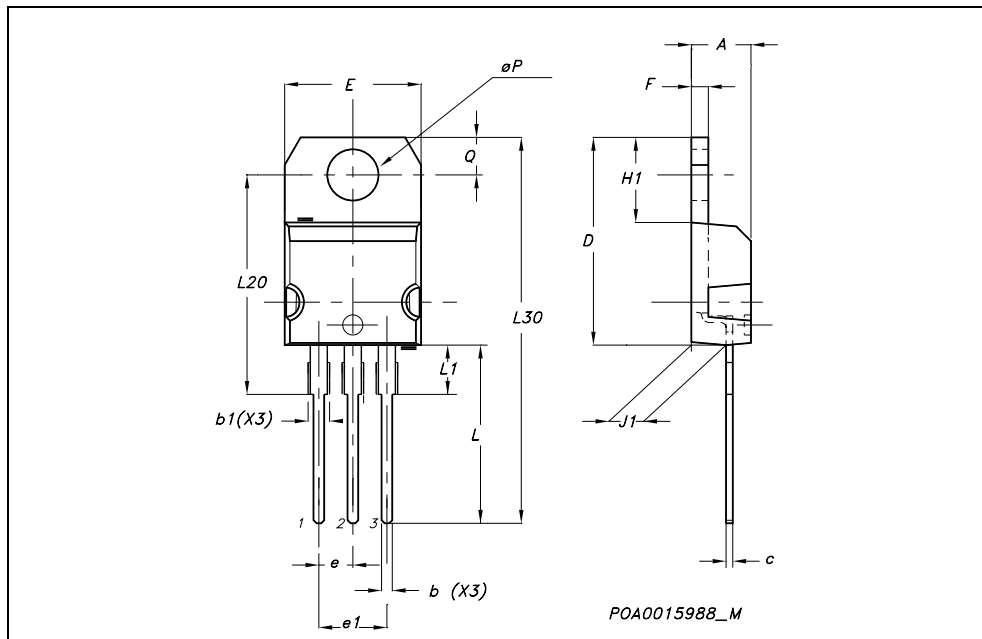
In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

TO-247 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.85		5.15	0.19		0.20
A1	2.20		2.60	0.086		0.102
b	1.0		1.40	0.039		0.055
b1	2.0		2.40	0.079		0.094
b2	3.0		3.40	0.118		0.134
c	0.40		0.80	0.015		0.03
D	19.85		20.15	0.781		0.793
E	15.45		15.75	0.608		0.620
e		5.45			0.214	
L	14.20		14.80	0.560		0.582
L1	3.70		4.30	0.14		0.17
L2		18.50			0.728	
øP	3.55		3.65	0.140		0.143
øR	4.50		5.50	0.177		0.216
S		5.50			0.216	

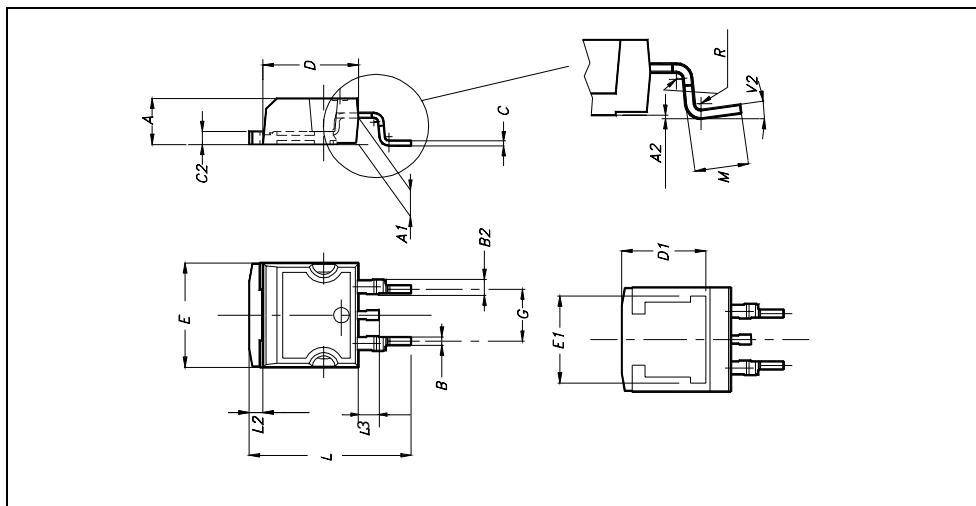


TO-220 MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.15		1.70	0.045		0.066
c	0.49		0.70	0.019		0.027
D	15.25		15.75	0.60		0.620
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.052
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
øP	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



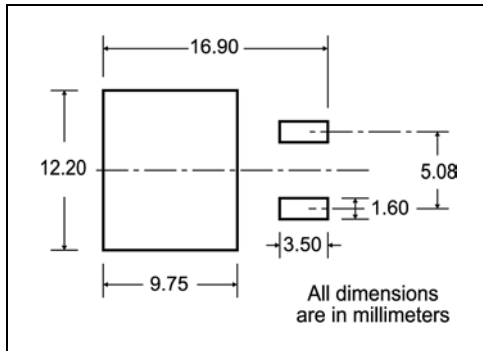
D²PAK MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
B	0.7		0.93	0.027		0.036
B2	1.14		1.7	0.044		0.067
C	0.45		0.6	0.017		0.023
C2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1		8			0.315	
E	10		10.4	0.393		
E1		8.5			0.334	
G	4.88		5.28	0.192		0.208
L	15		15.85	0.590		0.625
L2	1.27		1.4	0.050		0.055
L3	1.4		1.75	0.055		0.068
M	2.4		3.2	0.094		0.126
R		0.4			0.015	
V2	0°		4°			



5 Packaging mechanical data

D²PAK FOOTPRINT



TAPE AND REEL SHIPMENT

40 mm min. Access hole at slot location

Full radius

Tape slot in core for tape start 25mm min. width

G measured at hub

REEL MECHANICAL DATA

DIM.	mm		inch	
	MIN.	MAX.	MIN.	MAX.
A		330		12.992
B	1.5		0.059	
C	12.8	13.2	0.504	0.520
D	20.2		0.795	
G	24.4	26.4	0.960	1.039
N	100		3.937	
T		30.4		1.197

BASE QTY	BULK QTY
1000	1000

TAPE MECHANICAL DATA

DIM.	mm		inch	
	MIN.	MAX.	MIN.	MAX.
A0	10.5	10.7	0.413	0.421
B0	15.7	15.9	0.618	0.626
D	1.5	1.6	0.059	0.063
D1	1.59	1.61	0.062	0.063
E	1.65	1.85	0.065	0.073
F	11.4	11.6	0.449	0.456
K0	4.8	5.0	0.189	0.197
P0	3.9	4.1	0.153	0.161
P1	11.9	12.1	0.468	0.476
P2	1.9	2.1	0.075	0.082
R	50		1.574	
T	0.25	0.35	0.0098	0.0137
W	23.7	24.3	0.933	0.956

10 pitches cumulative tolerance on tape +/- 0.2 mm

Center line of cavity

User Direction of Feed

FEED DIRECTION

Bending radius

R min.

* on sales type

6 Revision history

Table 7. Revision history

Date	Revision	Changes
14-May-2003	1	First release
03-Mar-2006	2	Inserted TO-247. New template

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